

plate technique. With an SCFP technique, the I_{ON}/I_{OFF} ratio was increased from 1.3×10^4 to 2.4×10^4 . Meanwhile, the sub-threshold swing was also improved from 68.3 mV/dec to 64.1 mV/dec. The gate leakage was also reduced 64% (not shown here).

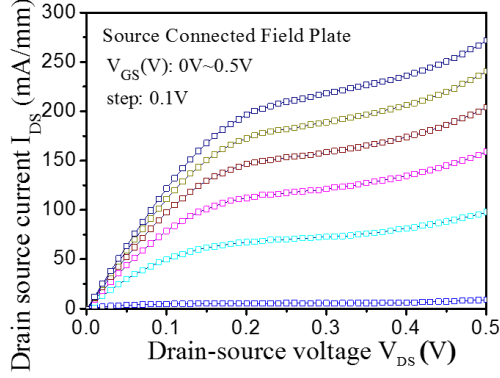


Fig. 2. DC characteristics of the enhanced mode InAs QWFET with source field plate (I_{DS} - V_{DS} curves).

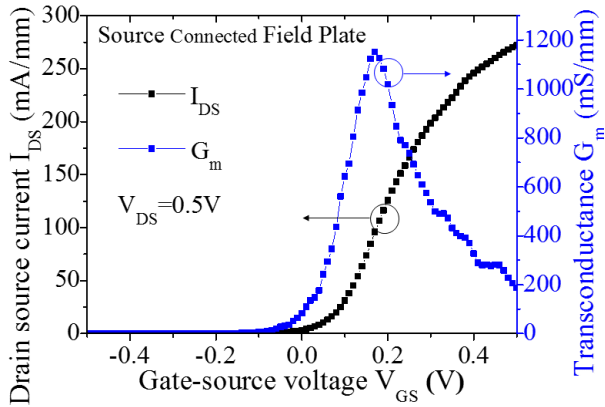


Fig. 3. Transfer characteristics of the enhanced mode InAs QWFET with source field plate at $V_{DS} = 0.5V$ (I_{DS} & G_m vs. V_{GS}).

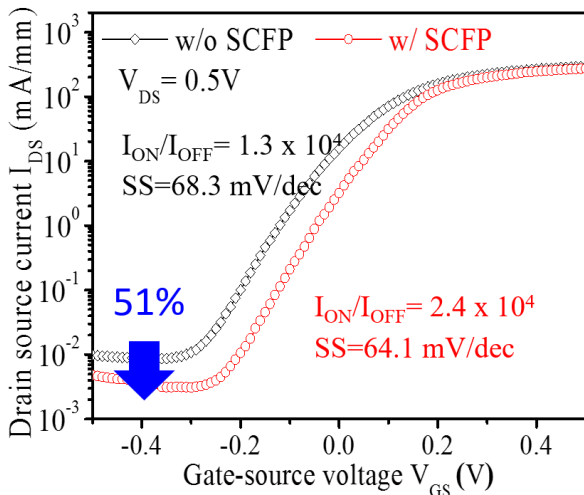


Fig. 4. SS & I_{ON}/I_{OFF} comparisons of the enhanced mode InAs with and without the source field plate technique at $V_{DS} = 0.5V$.

Fig. 5 shows the comparison of I_{ON}/I_{OFF} ratio as a function

of SS with other reported works of literature. Compared with other reports, the enhanced mode InAs QWFETs with the source connected field plate structure in this work demonstrated a high I_{ON}/I_{OFF} ratio of 2.4×10^4 with pretty small SS value of 64mV/dec. As the V_{DS} was increased to 1.0V, the better performance was achieved with a I_{ON}/I_{OFF} ratio of 1.0×10^5 and an extra low SS value of 61.3 mV/dec.

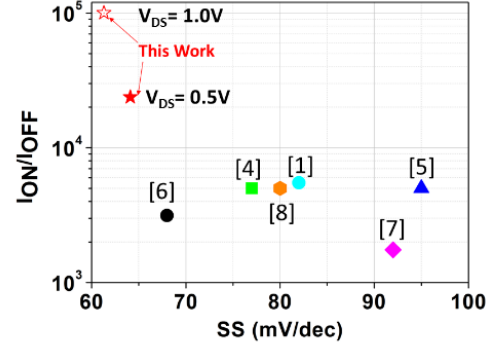


Fig. 5 I_{ON}/I_{OFF} vs. SS comparison of the normally-off SCFP InAs QWFET with other reported literature.[1], [4]–[8]

4. Conclusions

In this study, the enhanced mode InAs QWFETs with the source-connected field-plate structure were studied. The OFF-state current was 51% suppressed, and the gate leakage was 64% reduced compared with the conventional InAs QWFET. The excellent logic performance of SS = 64.1 mV/dec, DIBL = 44 mV/V and a high I_{ON}/I_{OFF} ratio of 2.4×10^4 were achieved. The results indicate that the enhanced mode InAs QWFETs with the source-connected field-plate is suitable for the low power logic applications.

Acknowledgements

This work was sponsored by NCTU-UCB I-RiCE program, Ministry of Science and Technology, Taiwan, under Grant No. MOST 106-2911-I-009-301. This work is particularly supported by "Aiming for the Top University Program" of the National Chiao Tung University and Ministry of Education, Taiwan, R.O.C

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